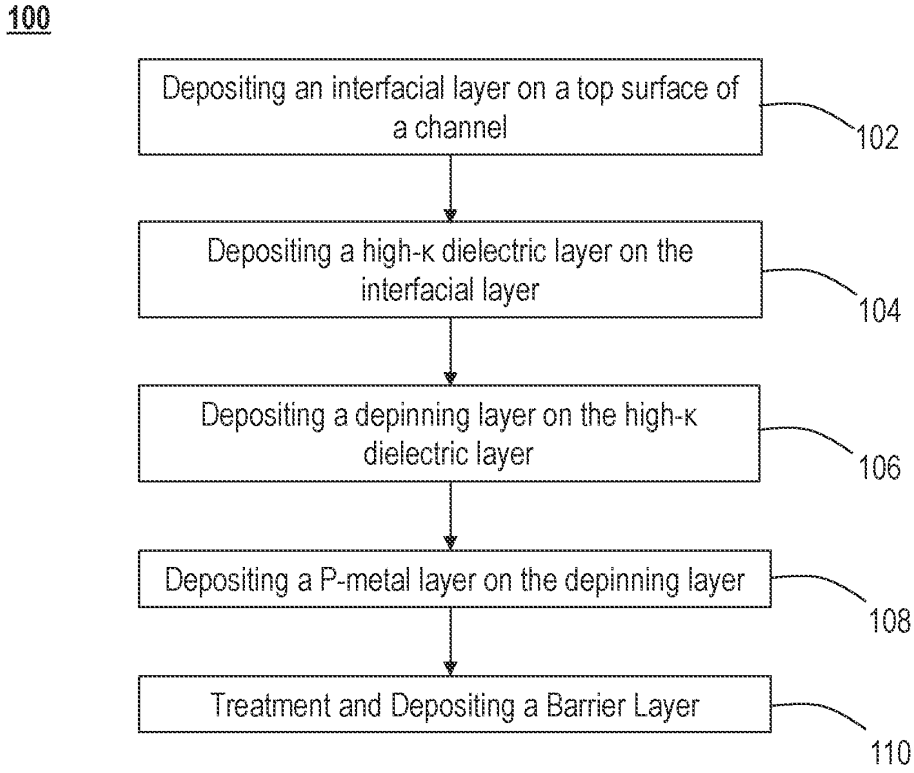

100
Depositing an interfacial layer on a top surface of a channel
102
Depositing a high-κ dielectric layer on the interfacial layer
104
Depositing a depinning layer on the high-κ dielectric layer
106
Depositing a P-metal layer on the depinning layer
108
Treatment and Depositing a Barrier Layer
110

FIG. 1

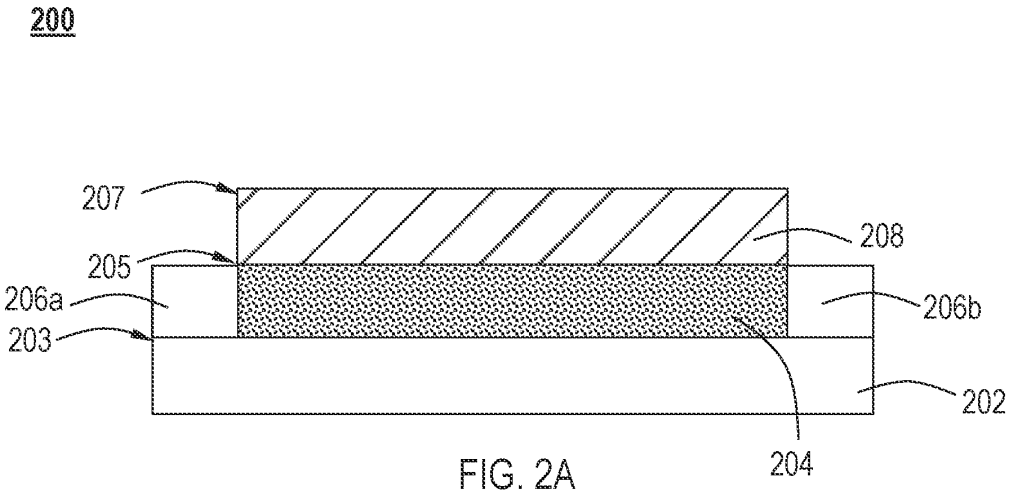

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206a
206b
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FIG. 2A

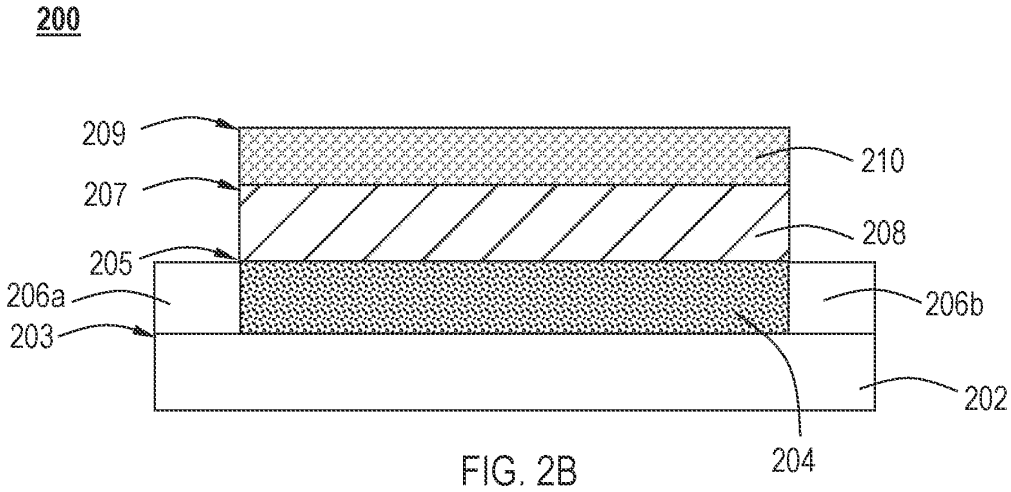

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206a
206b
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FIG. 2B

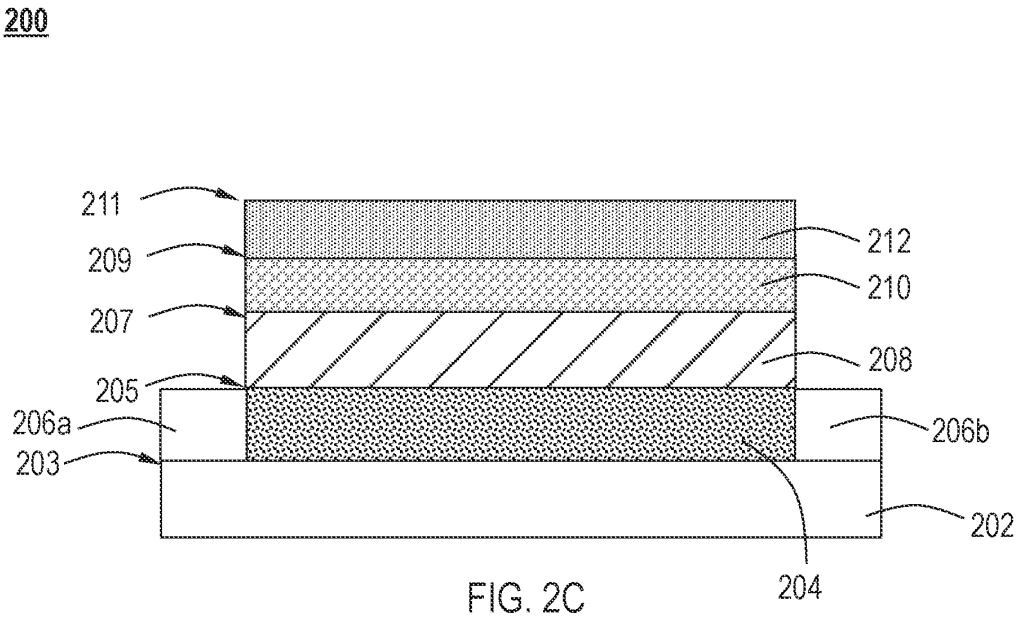

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206b
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FIG. 2C

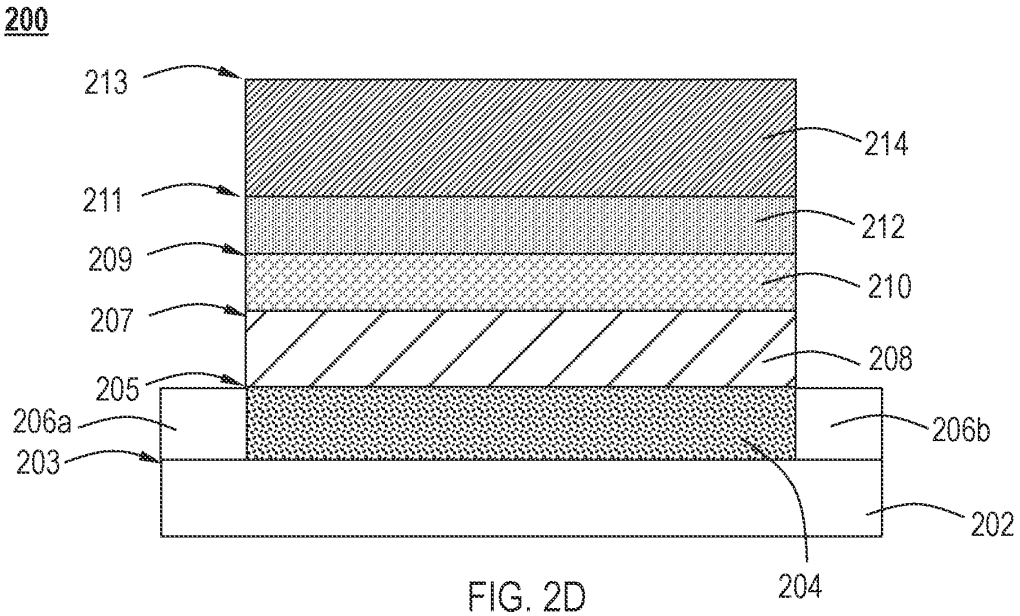

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206a
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206b
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FIG. 2D

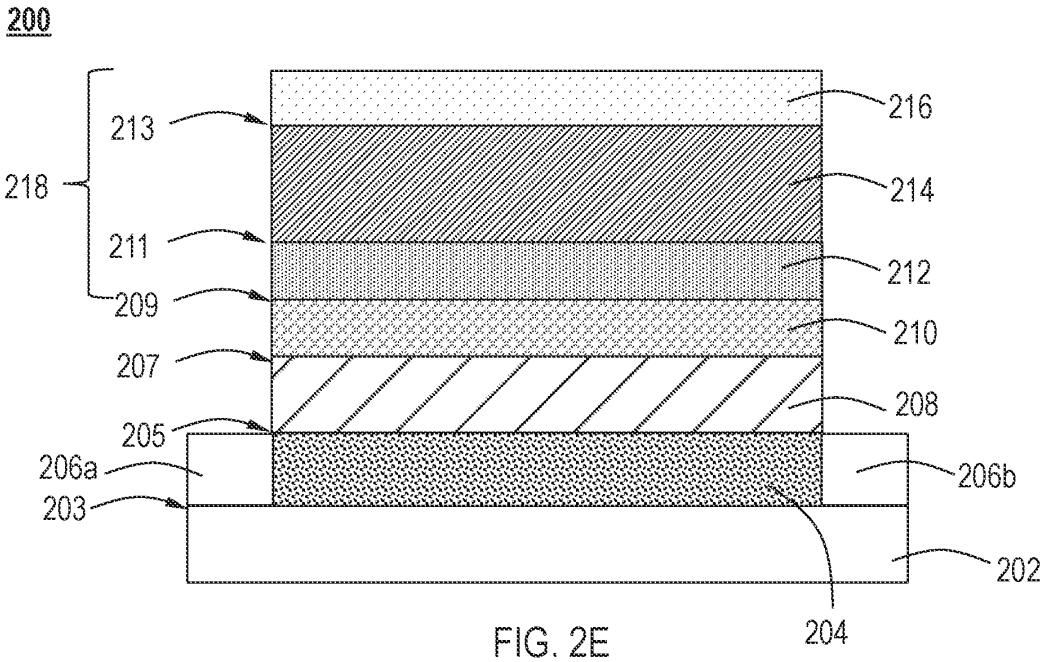

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206a
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206b
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FIG. 2E

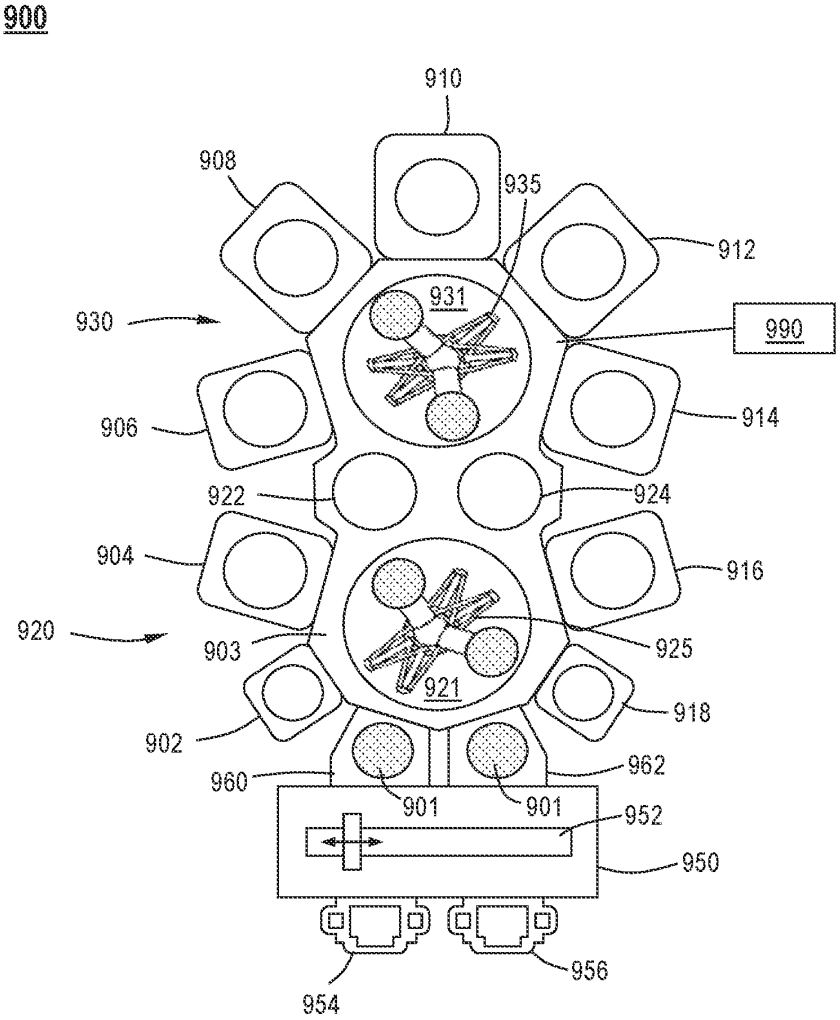

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FIG. 3